



Product Change Notification

Change Notification #: 116930 - 00

Change Title: Select Intel® SSD DC P4510 Series,
PCN 116930-00, Product Material,
Adding alternate DRAM vendors

Date of Publication: May 08, 2019

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	August 5, 2019
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Description of Change to the Customer:

Select Intel® SSD DC P4510 Series SKUs listed in the Product Affected Table below will have the following change.

- Two of the current 4Gb8 DRAM used on these products are being discontinued by the vendors Micron* and Hynix* respectively. Intel is adding 2 additional parts from Hynix* and Nanya* to the approved vendors to ensure that there is supply continuity for the product line.

Customer Impact of Change and Recommended Action:

This change has been thoroughly evaluated to ensure that there are no quality, reliability or functional implications to our customers. Intel is not recommending additional qualification of these changes on platforms received from Intel.

For your information only. No change to form fit or function. No change to Intel Ordering codes.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® SSD DC P4510 Series (1.0TB, 2.5in PCIe 3.1 x4, 3D2, TLC) Generic Single Pack	SSDPE2KX010T801	959391
Intel® SSD DC P4510 Series (1.0TB, 2.5in PCIe 3.1 x4, 3D2, TLC) Generic 10 Pack	SSDPE2KX010T810	959392
Intel® SSD DC P4510 Series (1.0TB, 2.5in PCIe 3.1 x4, 3D2, TLC) Generic Single Pack OPAL	SSDP2KX010T8OS	984815
Intel® SSD DC P4510 Series (1.0TB, 2.5in PCIe 3.1 x4, 3D2, TLC) Generic 10 Pack OPAL	SSDPE2KX010T8OP	984816

PCN Revision History:

Date of Revision:

May 8, 2019

Revision Number:

00

Reason:

Originally Published PCN



Product Change Notification

116930 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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